

**Electronic Patent Application Fee Transmittal****Application Number:**

10546897

**Filing Date:**

22-Aug-2003

**Title of Invention:**SEMICONDUCTOR COMPONENT HAVING THINNED DIE WITH CONTACT  
BUMPS AND POLYMER LAYERS ON SIX SIDES**First Named Inventor/Applicant Name:**

Warren M. Farnworth

**Filer:**

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**Attorney Docket Number:**

01-1059.1

Filed as Large Entity

**Utility under 35 USC 111(a) Filing Fees**

Description

Fee Code

Quantity

Amount

Sub-Total in  
USD(\$)**Basic Filing:****Pages:****Claims:****Miscellaneous-Filing:****Petition:****Patent-Appeals-and-Interference:****Post-Allowance-and-Post-Issuance:****Extension-of-Time:**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
Request for continued examination	1801	1	810	810
<b>Total in USD (\$)</b>				<b>810</b>